

**ASX RELEASE****16 October 2025****ASX: NVU**

## Ignite Investment Summit Hong Kong Presentation

**Nanoveu Limited (ASX: NVU, OTCQB: NNVUF) (“Nanoveu” or the “Company”)**, a technology innovator across advanced semiconductor, visualisation, and materials science, is pleased to advise of its participation at the Ignite Investment Summit being held this week in Hong Kong.

Nanoveu’s Chief Executive Officer of Semiconductor Technologies, Mr Mark Goranson, will be presenting the Company’s strategy for progressing its EMASS semiconductor division today at 12.00 pm AWST. Attached is the presentation that Mr Goranson will be speaking to at the conference.

This announcement has been authorised for release by the Board of Directors.

-ENDS-

### **Nanoveu Media**

Alfred Chong, Nanoveu MD and CEO

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E: [info@nanoveu.com](mailto:info@nanoveu.com)

### **About Nanoveu Limited**

Further details on the Company can be found at <https://nanoveu.com/>.

**EMASS** is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

**EyeFly3D™** is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS’s ultra-low-power SoC, powerful hardware.

**Nanoshield™** is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include *Nanoshield™ Marine*, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and *Nanoshield™ Solar*, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

**Forward Looking Statements** This announcement contains ‘forward-looking information’ that is based on the Company’s expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company’s business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as ‘outlook’, ‘ambition’, ‘anticipate’, ‘project’, ‘target’, ‘potential’, ‘likely’, ‘believe’, ‘estimate’, ‘expect’, ‘intend’, ‘may’, ‘mission’, ‘would’, ‘could’, ‘should’, ‘scheduled’, ‘will’, ‘plan’, ‘forecast’, ‘evolve’ and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company’s actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company’s actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

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# QEMASS

a  nanoveu business

## **IGNITE Investment Summit Presentation 2025**

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**AUTHORISATION** This document has been authorised for release by the Company's Board of Directors.

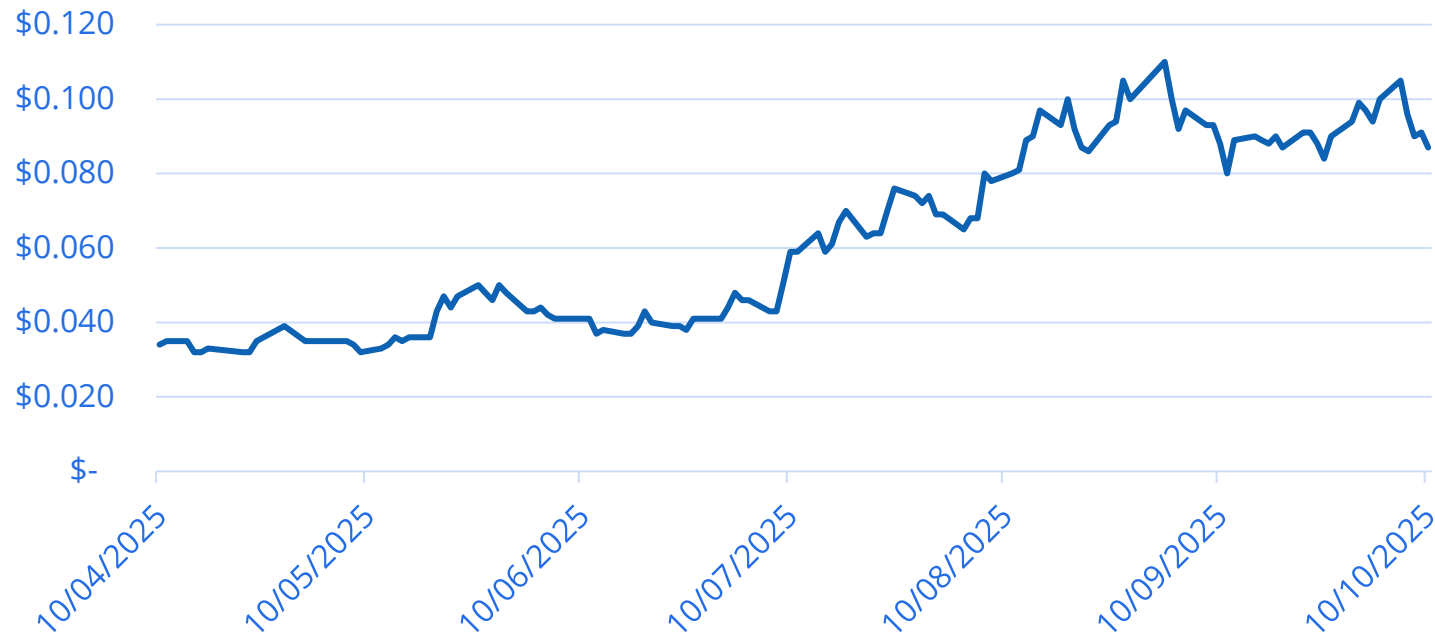
# Capital Structure

## Nanoveu Share Price

ASX - AUD

Nanoveu Limited (NVU.AX)

1D 5D 1M 6M YTD 1Y 5Y All



## Capital Structure\*

ASX Code	NVU
OTCQB Code	NNVUF
Shares on Issue	981.1m
Options on Issue	228.5m
Average Volume	13.6m
Market Cap	\$85.4m
Previous Close	\$0.087m

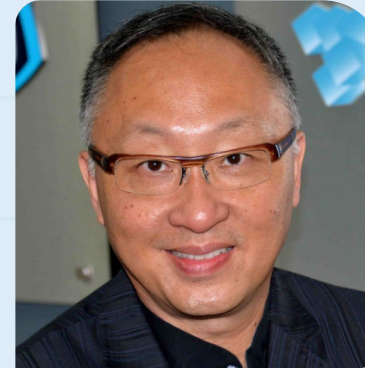
# Board and Management



**Dr. David Pevcic**

Executive Chairman

- Experienced professional and investor in the resources and technology sector
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8).
- Non-Executive Chairman at Infini Resources Ltd (ASX: I88).
- Holds a Bsc, MBBS, from the university of Western Australia.



**Alfred Chong**

Group CEO and Director

- Founder of Nanoveu, has 30+ years of experience in scaling companies and trade sales
- Former CEO of: Atex Media Command (APAC), THISS Technologies, 121View
- Former CMO at 3D International



**Michael Winlo**

Non-Executive Director

- Former CEO of Linear Clinical Research.
- Executive Director at Emyria Ltd (ASX:EMD)
- Former Health Lead at Palantir (NYSE:PLTR).
- Holds an MBA from Stanford and an MBBS from UWA.



**Steve Apedaile**

Non-Executive Director

- 30 years of experience in accounting
- Worked at KPMG and Horwath Hong Kong.
- Fellow of the ICAEW.
- Member of the AICD.
- Executive Chairman of Sprintex (ASX:SIX).

# Semiconductor Leadership Team



**Mark Goranson**

CEO of Semiconductor Technology

- VP of Global Ops, TE Connectivity
- SVP of Fab Ops, ON Semi
- VP of Fab Ops, Freescale
- Early Member of Intel



**Dr. Mohamed Sabry**

CTO, Founder of EMASS

- Associate Professor, NTU Singapore
- Postdoc, Stanford
- Recipient of Nanyang Education Award
- Ph.D. from EPFL



**Scott Smyser**

VP, Sales & Marketing

- EVP Marketing & BD, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP Sales, Atomica
- SVP Strategic Sales, Rockley Photonics

# EMASS Introduction

## Fabless Semiconductor Innovator in Edge AI Processing



- Ultra-low-power Edge AI SoCs for always-on intelligence in battery constrained devices
- Flagship ECS-DoT chip up to 20x more energy efficient than peers
- Usable across drones, wearables, IoT devices and other Edge AI applications

## Established Global Operations



- Global operations and R&D center's in USA, Singapore and Egypt
- 100% of EMASS acquired by Nanoveu Limited (ASX:NVU), March 2025

## Expert Team Across Disciplines

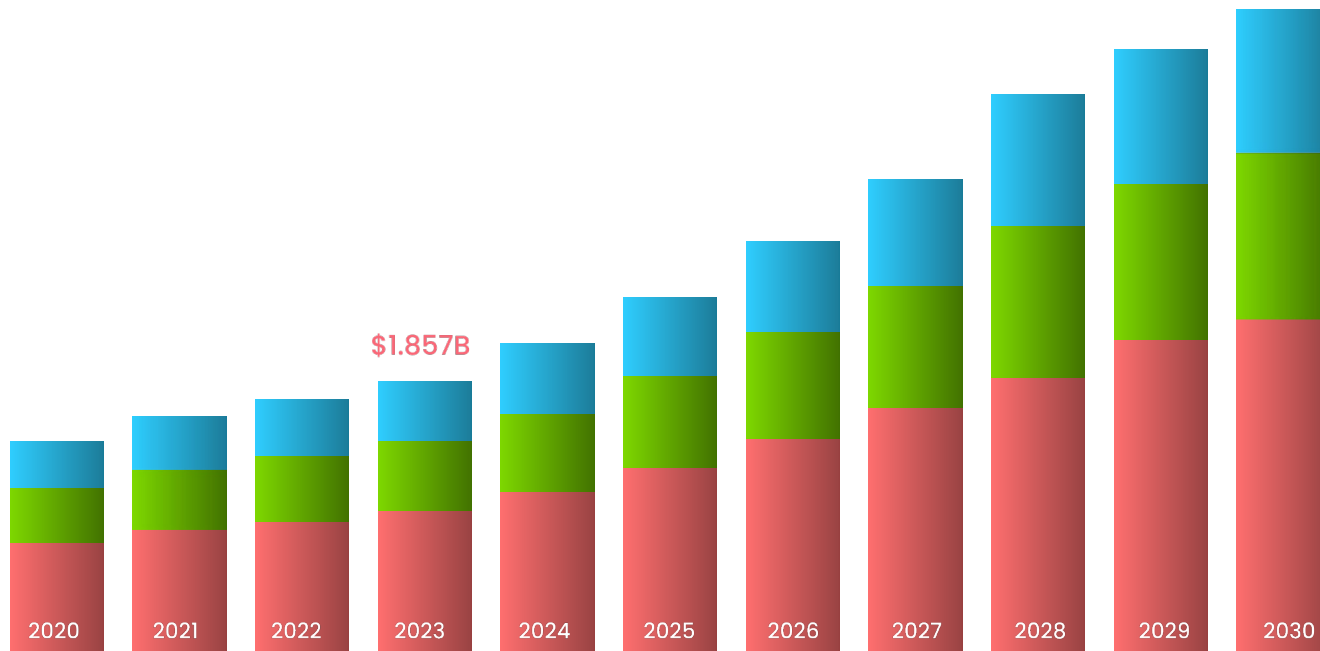


- Deep expertise in AI/ML, neural network acceleration, semiconductor design, sensor fusion, and embedded systems
- Experienced management with semiconductor and AI industry backgrounds

# Semiconductor & SoC Market Opportunity

## System On Chip Market Size

By Type 2020-2030 (USD Billion)



Source: Grand View Research

● Digital ● Analog ● Mixed

## SoC Market Growth:

Applications demanding continuous sensing, context awareness, and real-time decision-making



# Revolutionising Edge AI



## Edge AI Opportunities



Robust AI models require increased computation power and battery



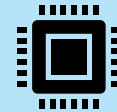
Current chips are not designed for efficient edge AI use cases



Devices need versatile chips with multi-sensor use-cases



## Edge AI Solution



Executes AI inference directly at the sensor under 1 mW power



Provides up to 20x energy efficiency vs leading chips



Enables smaller, lower-cost, and reconfigurable designs across drones, IoT, and wearables

# Introducing the ECS-DoT

Superior Performance, Low Power, Small Form Factor



Up to 12  
TOPs/Watt



Compressed  
AI Model < 2-bits



4  
MBytes



22nm technology  
with 7mm<sup>2</sup> die area



30 GOPs  
@ 50 MHz, 2mW



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# Redefining What's Possible in Ultra-Low-Power Edge AI

## Fully Programmable System on Chip

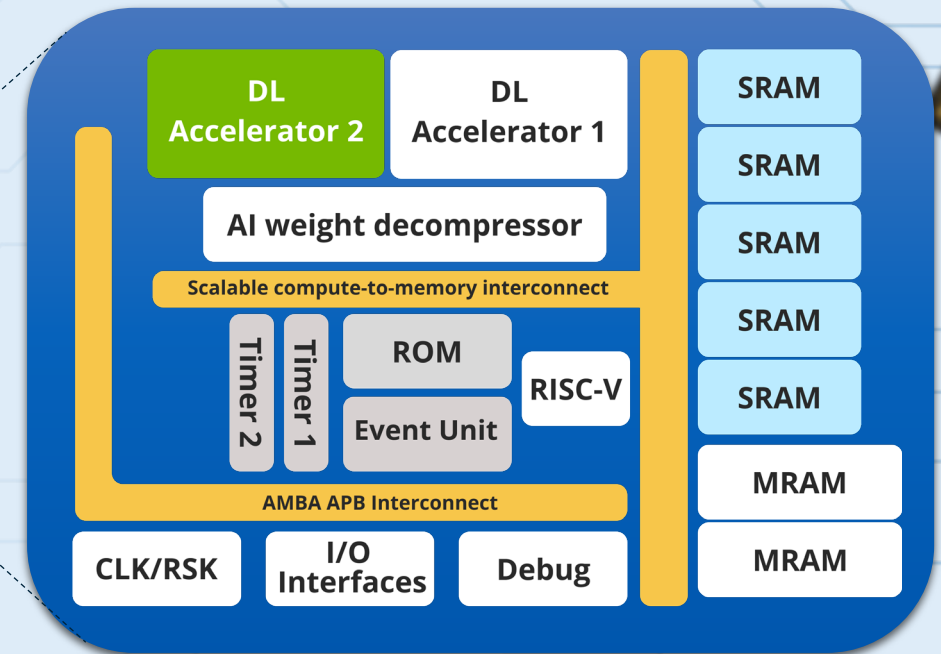
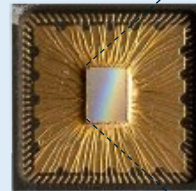
- Processor
- AI engines
- IPs for compressed AI

## Local decision-making at the Edge

- Always-on AI Inference
- Sensor Fusion
- Support CNNs, ML, Data Processing etc.

## Key Architecture Features

- <1 to 5 mW power consumption (Avg 2mW always on)
- No External DRAM needed (very fast on-chip SRAM and nonvolatile MRAM/RRAM)
- SW and HW support for highly compressed AI workloads

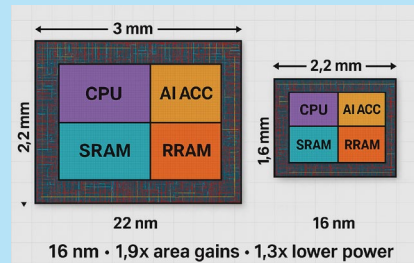


# Next Generation ECS-DoT

## Tape-out of Advanced 16nm Architecture

### Built on TSMC's 16nm Fin Field Effect Transistor (FinFET)

- Higher Perf. & Lower Power
- Smaller Die Size
- Production Ready



### Integrating Wireless Connectivity



Bluetooth 5.x +  
Bluetooth Mesh



Wi-fi



Lora for low-power,  
long-range (optional)

### Key architecture enhancements

- Single/Dual-core
- Improved AI performance with dynamic 1-16 bit precision
- Expanded support for AI operators: CNNs, Transformers, NLP, object detection

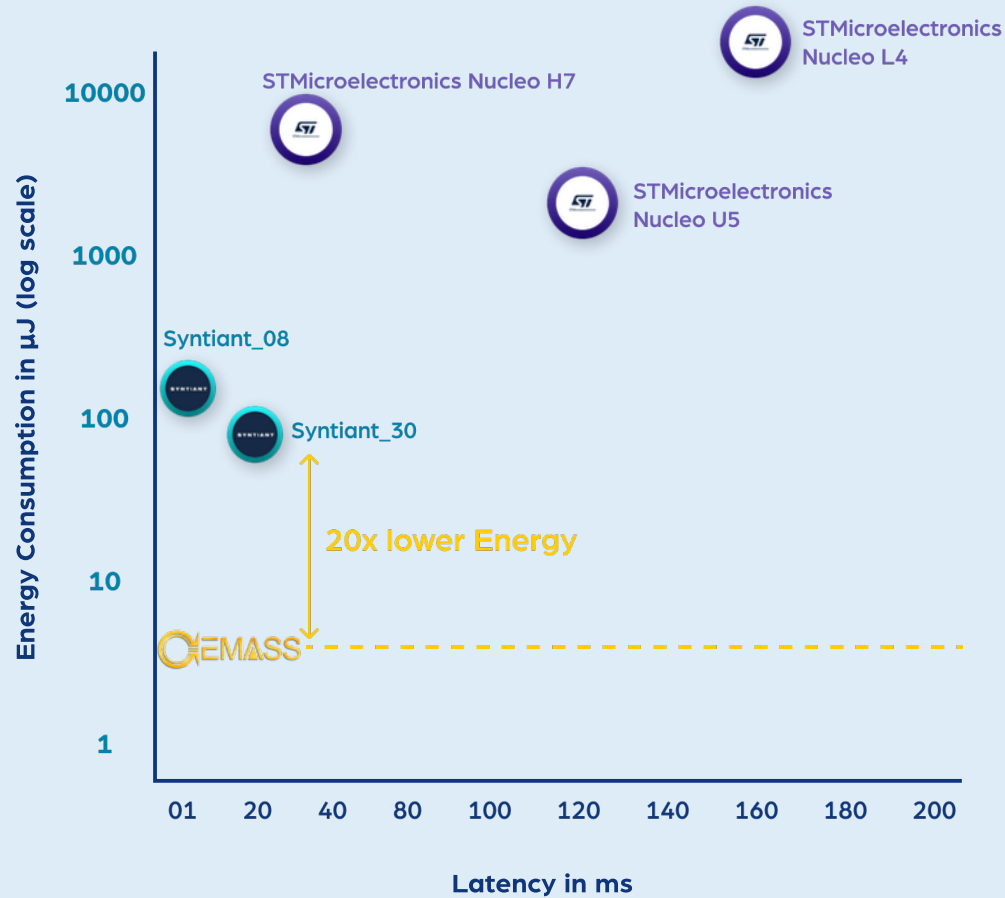
### Building for scalable edge AI deployment

- Edge autonomy: local sensing, AI processing, and wireless communication — all on one chip
- System cost reduction: fewer external components, smaller PCB
- Scalable platform for wearables, smart home, drones, industrial sensing, and more

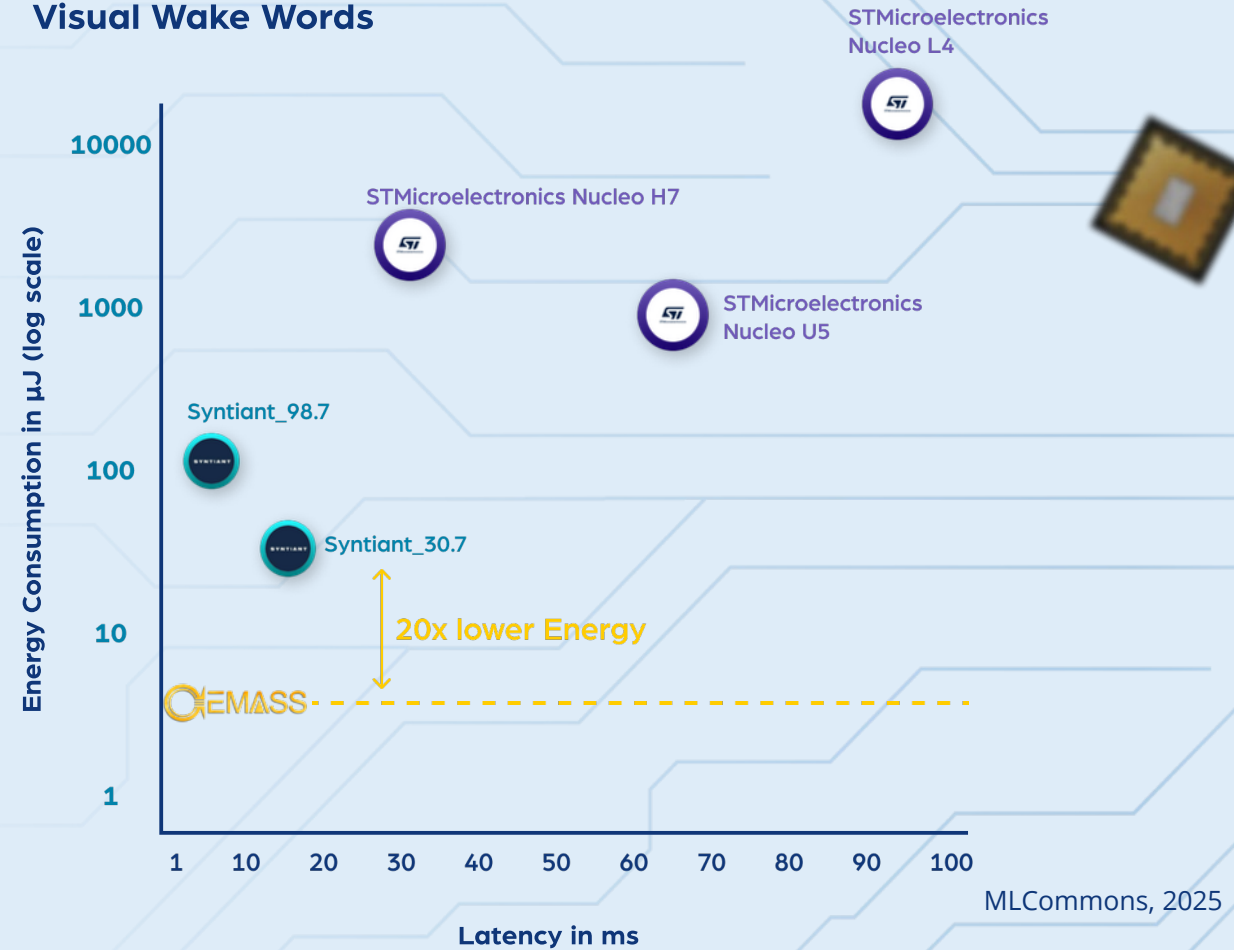
# Exceptional AI Computation

## 20X Lower Energy, Same Performance

Image Classification



Visual Wake Words



MLCommons, 2025

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# ECS-DoT Differentiation

## Full AI capability, true always-on operation

Key Attribute	ECS-DoT	Typical Alternatives
Compute Architecture	RISC-V + Dual Deep Learning Accelerators	General MCU, DSP, or fixed-function NNs
Memory Architecture	Fully on-chip (up to 8MB) — No external DRAM	External DRAM often required
Model Efficiency	Compressed models (~1.3 bits/weight)	Full-precision models, higher memory demand
Power Consumption	~2mW active power	10-50mW or higher
Always-On Performance	Optimized for continuous inference	Not designed for continuous sensing
Integration Complexity	Single-chip, minimal BOM	Complex multi-chip solutions
Supported Workloads	Neural networks + classical + sensor fusion	Often limited to specific NN types
Package Size	5mm x 5mm QFN-40	Often larger footprints
Target Applications	Audio, vision, sensor fusion, IoT, XR, wearables	More narrow or general-purpose



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# Target Edge AI Sectors

## Hearables

\$USD 138.5B by 2029

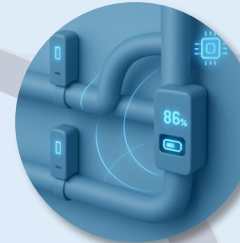
Source: [Marketsandmarkets](#)



## IoT Sensory

\$USD 168.69B by 2030

Source: [Mordor Intelligence](#)



## Wearables

\$USD 368.4B by 2035

Source: [Fact.MR](#)



## AR Glasses

\$USD 8.26B by 2030

Source: [Grand View Research](#)



## AI Cameras

\$USD 22.1B by 2028

Source: [Marketsandmarkets](#)



## Drones

\$USD 223.66B by 2034

Source: [Fact.MR](#)



# ECS-DoT Achieves Major Drone Performance Gains

Drone Type	Quadcopter	Hexacopter	Octocopter																																																														
Graph	<p>ECS-DoT Quadcopter Performance Improvements</p> <table border="1"> <caption>ECS-DoT Quadcopter Performance Improvements</caption> <thead> <tr> <th>Distance Per Unit Energy Improvements (in %)</th> <th>Number of Flights</th> </tr> </thead> <tbody> <tr><td>40%</td><td>1</td></tr> <tr><td>45%</td><td>5</td></tr> <tr><td>50%</td><td>7</td></tr> <tr><td>55%</td><td>16</td></tr> <tr><td>60%</td><td>24</td></tr> <tr><td>65%</td><td>20</td></tr> <tr><td>70%</td><td>17</td></tr> <tr><td>75%</td><td>7</td></tr> <tr><td>80%</td><td>2</td></tr> <tr><td>85%</td><td>1</td></tr> </tbody> </table>	Distance Per Unit Energy Improvements (in %)	Number of Flights	40%	1	45%	5	50%	7	55%	16	60%	24	65%	20	70%	17	75%	7	80%	2	85%	1	<p>ECS-DoT Hexacopter Performance Improvements</p> <table border="1"> <caption>ECS-DoT Hexacopter Performance Improvements</caption> <thead> <tr> <th>Distance Per Unit Energy Improvements (in %)</th> <th>Number of Flights</th> </tr> </thead> <tbody> <tr><td>45%</td><td>1</td></tr> <tr><td>50%</td><td>8</td></tr> <tr><td>55%</td><td>21</td></tr> <tr><td>60%</td><td>27</td></tr> <tr><td>65%</td><td>25</td></tr> <tr><td>70%</td><td>11</td></tr> <tr><td>75%</td><td>6</td></tr> </tbody> </table>	Distance Per Unit Energy Improvements (in %)	Number of Flights	45%	1	50%	8	55%	21	60%	27	65%	25	70%	11	75%	6	<p>ECS-DoT Octocopter Performance Improvements</p> <table border="1"> <caption>ECS-DoT Octocopter Performance Improvements</caption> <thead> <tr> <th>Distance Per Unit Energy Improvements (in %)</th> <th>Number of Flights</th> </tr> </thead> <tbody> <tr><td>35%</td><td>2</td></tr> <tr><td>40%</td><td>4</td></tr> <tr><td>45%</td><td>5</td></tr> <tr><td>50%</td><td>12</td></tr> <tr><td>55%</td><td>21</td></tr> <tr><td>60%</td><td>14</td></tr> <tr><td>65%</td><td>17</td></tr> <tr><td>70%</td><td>10</td></tr> <tr><td>75%</td><td>8</td></tr> <tr><td>80%</td><td>4</td></tr> <tr><td>85%</td><td>3</td></tr> </tbody> </table>	Distance Per Unit Energy Improvements (in %)	Number of Flights	35%	2	40%	4	45%	5	50%	12	55%	21	60%	14	65%	17	70%	10	75%	8	80%	4	85%	3
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Performance Gains	Achieved up to <b>80% improvement</b> in mission endurance, with a <b>60% average</b> extended flight time over baseline	Delivered up to <b>75% improvement</b> in flight endurance, with an average	Delivered consistent flight <b>endurance up to 85% with an average 57%</b> improvement																																																														

# Building Commercial Momentum

## OEM Sales Network Buildout



Wearables



Drones



Hearables

## What Market Is Responding To:

### Ultra-low power AI inference

- < 10 ms vs. 150-300 ms for competitors
- Up to 20X lower energy consumption vs. competitors

### AI Model Portability

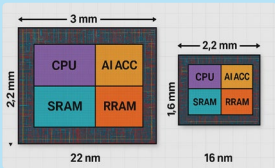
- Supports a wide range of AI Models
- Fast and easy development cycle
- Interoperability

### Multi Sensor Integration

- Seamless integration with a variety of sensor types
- Real-time fusion of audio, motion and environmental data

# Upcoming Catalysts

## 16nm Tape-out projected in Q4



### Smaller with higher performance

- ~200% smaller and 1.3x less power
- Our highest performing ECS-DoT



### Increased AI Performance

- Dynamic 1-16 bit precision with less power
- Increased AI model support

## Ongoing OEM engagement for 22nm technology



### New Evaluation Board

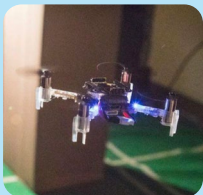
- 800% smaller and easier to use
- Allows for convenient customers testing



### What is resonating with OEMs

- Up to 20x lower energy consumption
- Smaller batteries and sleeker product design

## Live drone benchmarking



### Transition to live drone trails

- Trails aim to validate the 50%+ endurance gains during simulation



### Drone Market Validation

- Allows EMASS to increase partnerships and sales in the Drone Market



**Thank You**

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